



MT29C8G96MAZBBDJV-48 IT

Specs

SIM MODELS & SOFTWARE

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DOCUMENTATION & SUPPORT

WHERE TO BUY

Specs

Orderable Parts for: MT29C8G96MAZBBDJV-48 IT

SEE ALL 8GB NAND-BASED MCP PARTS

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29C8G96MAZBBDJV-48 IT	Production	N/A	JWB31	N/A	N/A	No		N/A

Detailed Specifications

NAND Density	8Gb	DRAM Type	LPDDR	DRAM Density	4Gb	Part Status Code	Production
Width	x16	Secondary Width	x16	RoHS	Yes	Voltage	1.7V-1.9V
Package	VFBGA	Pin Count	168-ball	Clock Rate	208 MHz	Op. Temp.	-40C to +85C
Pinout							

Sim Models & Software

Sim Model (5)

Title & Description	Updated	Type	
IBIS MCP-J4X3_IT (M60A+T79M) 137b, 168b (zip) Rev 2.0 (MCP: J4X3, 137b, 168b)	08/2014	Sim Model	ADD EMAIL
IBIS (zip) Rev 2.0 - 8Gb x16 NAND Flash with 4Gb x32 LPDDR MCP: MT29C8G96MAZBBDK-48 IT, MT29C8G96MAZBBDJV-48 IT (MCP: 137b, 168b, J4R3 (M60A, T89M))	11/2014	Sim Model	ADD EMAIL
IBIS (zip) Rev 2.0 - 4Gb x16 NAND Flash with 4Gb x32 LPDDR MCP (MCP: 168b, J4R2 (M60A, T89M))	02/2015	Sim Model	ADD EMAIL
IBIS (zip) Rev 1.0 - 4Gb x8 NAND Flash with 2Gb 2x16 LPDDR2 MCP (MCP: 162b, J80F (M70M, U98M))	03/2015	Sim Model	ADD EMAIL
IBIS (zip) Rev 1.0 - 4Gb x8 NAND Flash with 8Gb x32 LPDDR3 MCP (MCP: 221b, J4F2 (V91M, M60A))	04/2015	Sim Model	ADD EMAIL

RoHS Certificates

Title & Description	Updated	Type	
RoHS Certificate of Compliance (PDF) Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.	04/2015	RoHS Certification	ADD EMAIL
China RoHS Certificate (PDF) Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.	04/2015	RoHS Certification	ADD EMAIL

Documentation & Support

Technical Note (9)

Title & Description	Updated	Type	
Recommended Soldering Parameters (pdf) Defines the recommended soldering techniques and parameters for Micron Technology, Inc., products. (TN-00-15)	12/2012	Technical Note	ADD EMAIL
TN-10-21: Qualcomm QSC6695 Register Settings (pdf) Rev. 1.0 (TN-10-21)	12/2011	Technical Note	ADD EMAIL
TN-10-21: Qualcomm QSC6695 Validation Report (pdf) Rev. 1.0 (TN-10-21)	12/2011	Technical Note	ADD EMAIL
Bypass Capacitor Selection for High-Speed Designs (pdf) Describes bypass capacitor selection for high-speed designs. (TN-00-06)	03/2011	Technical Note	ADD EMAIL
Micron Wire-Bonding Techniques (pdf) This technical note provides guidance on wire bonding techniques for both nickel-palladium (NiPd) and aluminum (Al) bond pads on Micron products. (TN-00-22)	11/2010	Technical Note	ADD EMAIL

SEE ALL RESULTS

Customer Service Note (6)

Title & Description	Updated	Type	
Shipping Quantities (pdf) Provides standard part quantities for shipping. (CSN-04)	01/2015	Customer Service Note	ADD EMAIL
Micron BGA Manufacturer's User Guide (pdf) Provides information to enable customers to easily integrate both leading-edge and legacy Micron's ball grid array (BGA) packages into their manufacturing processes. It is intended as a set of high-level guidelines and a reference manual describing typical package-related and manufacturing process-flow practices. (CSN-33)	12/2014	Customer Service Note	ADD EMAIL
Micron Component and Module Packaging (pdf) Explanation of Micron packaging labels and procedures. (CSN-16)	11/2014	Customer Service Note	ADD EMAIL
Product Marks/Product and Packaging Labels (pdf) Explains product part marking, and product and packaging labels. (CSN-11)	10/2014	Customer Service Note	ADD EMAIL
PCN/EOL Systems (pdf) Explains Micron's product change notification and end-of-life systems. (CSN-12)	04/2012	Customer Service Note	ADD EMAIL

SEE ALL RESULTS

Tool (2)

Title & Description	Updated	Type	
FBGA Decoder Micron's FBGA Part Marking Decoder makes it easier to understand part marking.	12/2014	Tool	ADD EMAIL
PISMO2 Boards (html) The platform-independent storage module PISMO™ specifications provides a standard for convenient, interchangeable memory test boards. PISMO boards significantly reduce design inefficiencies, providing a huge benefit for the short development cycles of consumer products.	10/2008	Tool	ADD EMAIL

Where to Buy

Orderable Parts

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MT29C8G96MAZBBDJV-48 IT	Production	N/A	JWB31	N/A	N/A	No		N/A

Contact Your Sales Rep

- OR - Check with Distributors

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